

■ Enabling under 65nm technologies for void-free Cu fill.

- ◆ Conformal liner/barrier film achieve the high density.
- ◆ Enhanced bottom and sidewall coverage.
- ◆ Minimized overhang at the top corners.

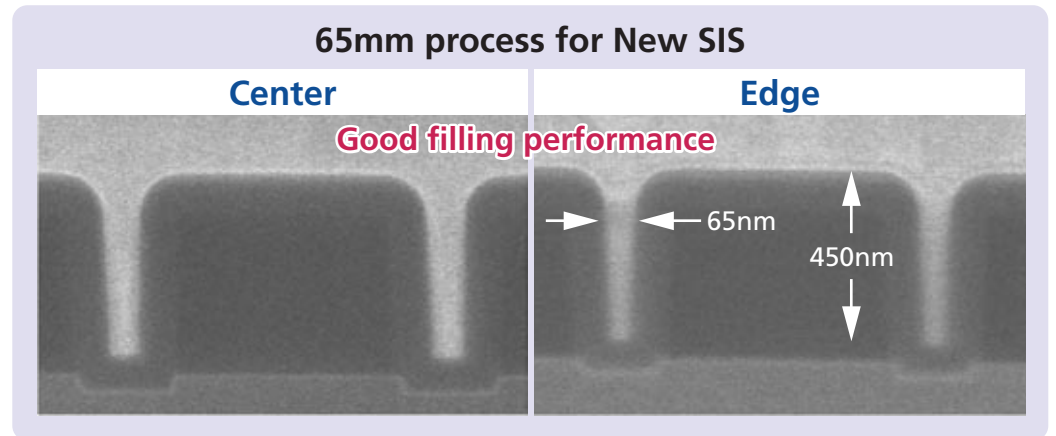


ULVAC Solutions

■ PVD

- LTS (Long Throw Sputtering)
- SIS (Self-Ionized Sputtering)
- New SIS

■ CVD: WN-CVD, New Metal CVD



Systems

Spin Coater

SOD SYSTEM
ULVAC, Inc.



Annealing

Vertical Furnace V-Series
ULVAC, Inc.



Ion Implanter

IW-630
ULVAC, Inc.



ENTRON
ULVAC, Inc.



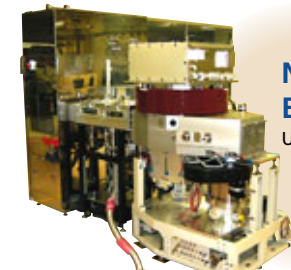
Sputtering

CERAUS Zi-1000N
ULVAC, Inc.



Etching

New Concept Etcher
ULVAC, Inc.



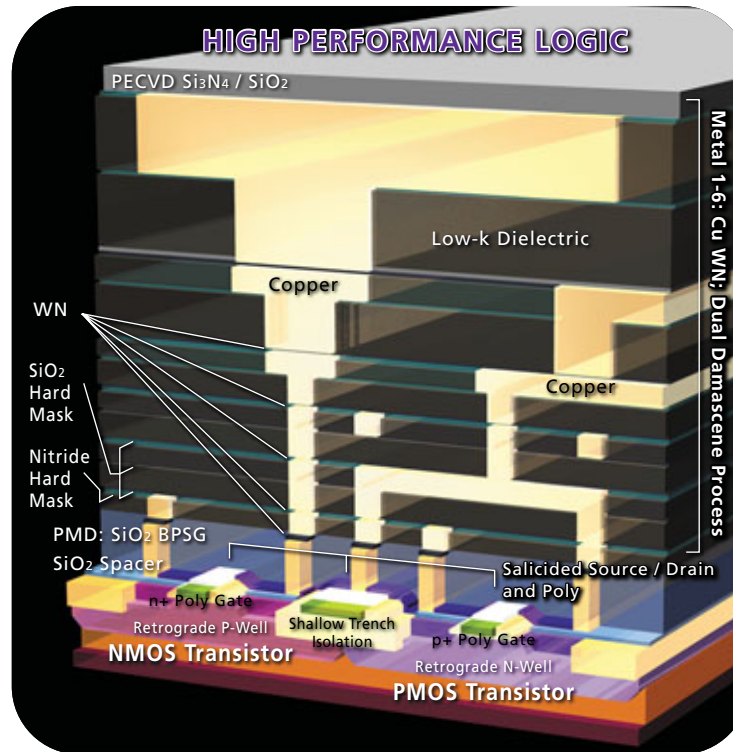
Resist Stripping

enviro™
ULVAC, Inc.



Compact Annealing

RTA-8000
ULVAC-RIKO, Inc.



Components

Analyzer / Measurement



**PHI Quantera SXM
PHI 700**
ULVAC-PHI, Inc.



GI-M2
ULVAC, Inc.



REPOS
ULVAC, Inc.



MESEC
ULVAC, Inc.



HELIOT
ULVAC, Inc.

Vacuum Pump



LR/HR Series
ULVAC, Inc.



**UTM-FW/FH
Series**
ULVAC, Inc.



CRYO-U 12H
ULVAC CRYOGENICS, INC.

Material



Target
ULVAC Materials, Inc.



VPT-030
ULVAC KICO, Inc.